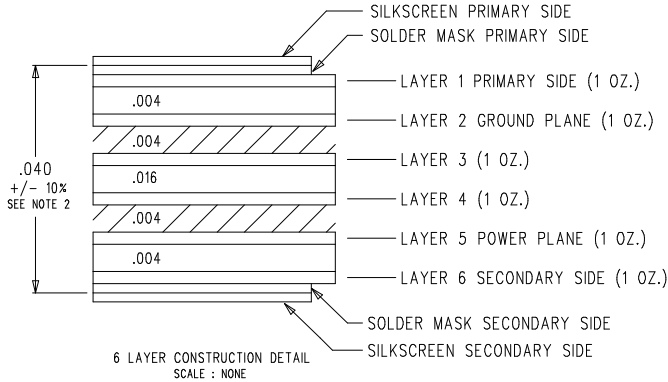
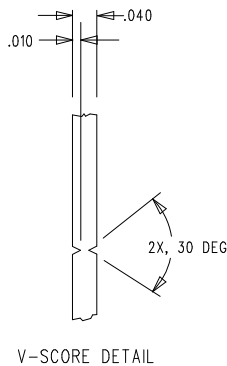
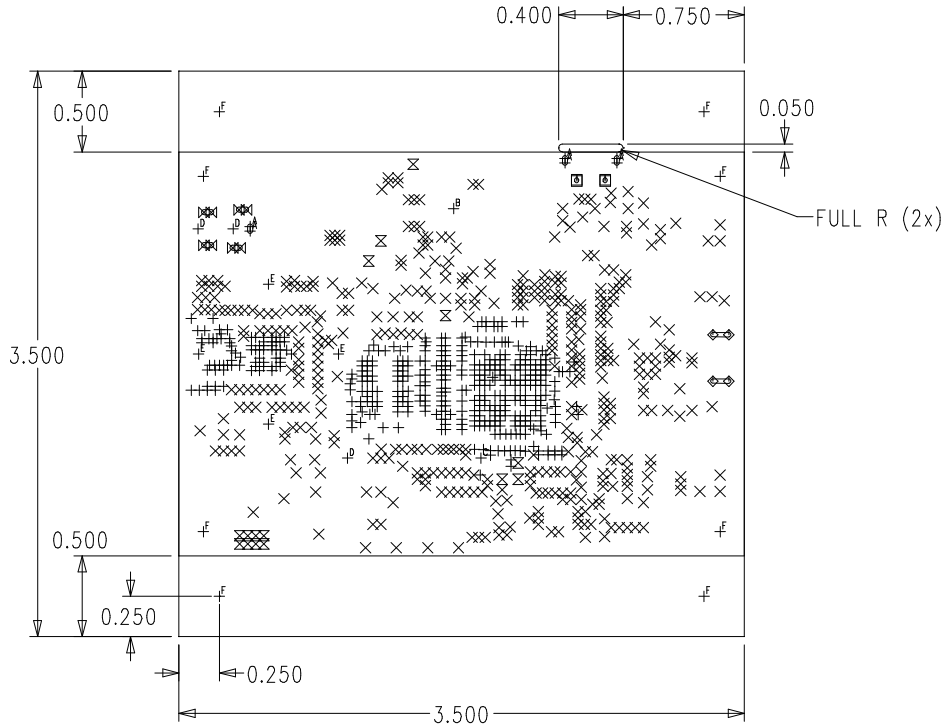



SIZE	QTY	SYM	PLATED	TOL
0.006	433	+	YES	+0.003/-0.006
0.012	458	×	YES	+0.003/-0.012
0.026 x 0.034	2	□	YES	+/-0.003
0.028	15	⊠	YES	+/-0.003
0.028 x 0.126	2	◇	YES	+/-0.003
0.032 x 0.078	4	⊠	YES	+/-0.003
0.032 x 0.06	3	+ <sup>A</sup>	YES	+/-0.003
0.04	1	+ <sup>B</sup>	YES	+/-0.003
0.044	1	+ <sup>C</sup>	NO	+/-0.003
0.063	3	+ <sup>D</sup>	NO	+/-0.003
0.07	4	+ <sup>E</sup>	NO	+/-0.003
0.125	8	+ <sup>F</sup>	NO	+/-0.005



REVISIONS				
REV	DESCRIPTION OF CHANGE	DRFTR	DATE	APPROVED
0.1	NEW RELEASE	C.C.D.	03/03/14	
1.0	UPDATED PER ECO	C.C.D.	10/13/14	
1.1	UPDATED PER ECO	C.C.D.	02/16/15	
2.0	UPDATED PER ECO	C.C.D.	04/23/15	

UNLESS OTHERWISE SPECIFIED

- BOARD TO BE FABRICATED PER IPC-6012A, CLASS 2.
- MATERIAL: POLYCLAD FR-370HR OR EQUIVALENT. OUTER LAYERS 1/2 OZ/SQFT CU  
INNER LAYERS 1 OZ/SQFT CU FINISHED .040 +/-10% (.SEE DETAIL).  
VENDOR MAY ADJUST THICKNESS TO FULFILL NOTE 9.
- PLATING: ADDITIONAL CU PLATING 1/2 OZ/SQFT  
ALL HOLES PLATED THROUGH, EXCEPT AS NOTED IN HOLE LEGEND.  
MINIMUM PTH BARREL THICKNESS = 0.0008" MINIMUM AVERAGE  
PER IPC-6012A WITH AMENDMENT 1, CLASS 2 REQUIREMENTS.  
WITH NO SINGLE MEASUREMENT LESS THAN 0.00071 IN THE PLATED HOLES.
- FINISH: SURFACES TO BE COATED BY ENIG OF 2 TO 10 MICROINCHES OVER  
A MINIMUM OF 60-200 MICROINCHES OF LOW STRESS NICKEL.  
NO ADDITIONAL ELECTROLYTIC HARD GOLD IS REQUIRED FOR CONTACTS.
- SOLDERMASK: SOLDER MASK TO BE TRANSPARENT GREEN LPI BOTH SIDES PER GERBER FILES.
- SILKSCREEN: WHITE EPOXY INK, APPLY TO BOTH SIDES PER GERBER FILES.
- ARTWORK: MINIMUM FEATURE SIZE = 0.0035  
MINIMUM AIR GAP = 0.0035
- ALL DIMENSIONS ARE IN INCHES.
- CONTROLLED IMPEDANCE: BOARD TO BE BUILT TO YIELD CONTROLLED IMPEDANCE OF:  
100 OHMS DIFF/PAIR (+/-10%) ON ALL .0045" LINE WIDTHS  
90 OHMS DIFF/PAIR (+/-10%) ON ALL .0055" LINE WIDTHS  
60 OHMS SINGLE/ENDED (+/-10%) ON ALL .005" LINE WIDTHS ON LAYERS 1 & 6  
50 OHMS SINGLE/ENDED (+/-10%) ON ALL .005" LINE WIDTHS ON LAYERS 3 & 4
- DO NOT ADD NON-FUNCTIONAL COPPER THEIVING ON OPEN AREAS OF OUTER LAYERS.  
THEIVING IS ALLOWED ON INNER LAYERS, UNLESS OTHERWISE SPECIFIED.
- VIAS SHOULD BE COVERED ACCORDING TO ONE OF THE FOLLOWING METHODS.  
METHOD 1 IS PREFERRED.  
METHOD 1: VIAS MUST BE FILLED WITH SOLDERMASK MATERIAL AFTER  
ELECTROLESS NICKEL/IMMERSION GOLD AND BEFORE PRIMARY LPI MASK. AFTER THE  
FILL IS CURED, THE PRIMARY MASK IS THEN APPLIED WITH NO VIA APERTURES  
BOTH SIDES.  
METHOD 2: AFTER APPLICATION OF FULL BODY ELECTROLESS NICKEL/IMMERSION  
GOLD, APPLY PRIMARY MASK WITH REDUCED VIA APERTURES THAT ARE 6 MILS  
LARGER THAN DRILLED HOLE DIAMETER BOTH SIDES. THEN APPLY SOLDER MASK  
PLUG ON COMPONENT SIDE.
- VIA HOLES (.006 & .012) REQUIRE TANGENCY ONLY, INSTEAD OF ANNULAR RING.
- TEARDROP PADS ARE ACCEPTABLE WHERE NEEDED.
- BUILD AS 1-UP PCB.
- USE IPC-D-356A NETLIST AS SUPPLIED FOR CHECKING.  
THE FOLLOWING NETS ARE INTENTIONALLY SHORTED:  
GND & AGND @ W1 (LAYER 1)
- V SCORE 2 LINES ON BOTH SIDES OF THE BOARD. SEE DETAIL.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE : .xx +/- .010 .xxx +/- .005	CONTRACT NO.		 20 Cotton Road Nashua, New Hampshire 03063 (603) 883-2430 FAX (603) 882-2655	
	APPROVALS	DATE		
MATERIAL	DRAWN	C.C.D.	04/23/15	FABRICATION DRAWING BLIP2
SEE NOTES	CHECKED			
FINISH	ENGINEERING			SIZE B DWG. NO. A0573-2013 REV. 2.0
SEE NOTES	QUALITY			
DO NOT SCALE THIS DRAWING	MANUFACTURING		SCALE 1 : 1	SHEET 1 OF 1